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Description

CONDUCTIVE THERMOPLASTIC-RESIN FILM AND CONDUCTIVE
THERMOPLASTIC-RESIN LAMINATE FILM

Cross Reference to Prior Application

This is a U.S. national phase application under 35 U.S.C. §371 of International Application No. PCT/JP2005/005429 filed March 24, 2005 and claims the benefit of Japanese Applications No. 2004-086809, filed March 24, 2004 and 2004-095040, filed March 29, 2004. The International Application was published in Japanese on September 29, 2005 as International Publication No. WO 2005/090452 under PCT Article 21(2).

Technical Field

[0001]

The present invention relates to a thermoplastic-resin film and a thermoplastic-resin laminate film each having excellent electrical conductivity. More particularly, the invention relates to the thermoplastic-resin film and thermoplastic-resin laminate film further excellent in water vapor barrier properties and/or tackiness.